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Response
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Sunder

IN THE UNITED STATES
PATENT AND TRADEMARK OFFICE

In re Patent Application of:

Inventor:	Chen, et al	Confirmation No:	1660
Serial No.	10/085,866	Examiner:	Hu, Shouxiang
Filed:	Feb 27, 2002	Group Art Unit:	2811
Title:	Emission Layer Formed By Rapid Thermal Formation Process		

Commissioner for Patents
P O BOX 1450
Alexandria VA 22313-1450

RESPONSE TO RESTRICTION REQUIREMENT

In response to your Office Action/Restriction Requirement dated July 1, 2003;
Applicants affirm the election of Group II, (Claims 13-19) without traverse.

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(541) 715-4197

Respectfully submitted,

Chen, et al

By: Timothy F. Myers
Timothy F. Myers, Reg No: 42,919
Attorney For Applicants

I hereby certify that this correspondence is being deposited on the date indicated below with the United States Postal Service as first class mail in an envelope addressed to: Commissioner for Patents, PO Box 1450, Alexandria, VA 22313.

Timothy F. Myers
Signature
Timothy F. Myers
Typed Name
7/23/03
Date of Signature

10013802

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In Re U.S. Patent Application

Applicant: Chen et al.

Serial No.: 10/085866

Filing Date: Feb 27 2002

For: EMISSION LAYER FORMED BY
RAPID THERMAL FORMATION
PROCESS

Art Unit: Unassigned



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PRELIMINARY AMENDMENT

Assistant Commissioner for Patents
Washington, D.C. 20231

Dear Sir:

Prior to consideration and calculating the fees for the above-referenced
Application, please amend the Application as follows:

In the Specification:

Please replace the paragraph beginning on page 3, line ³⁰~~20~~, with the
following rewritten paragraph:

A¹ Referring now to FIG. 1, a preferred embodiment emitter 10 of the
invention is shown in a two-dimensional schematic cross section. The preferred
embodiment emitter 10 is a metal-insulator-semiconductor (MIS) device including a flat